

GLASS PASSIVATED FAST RECOVERY BRIDGE RECTIFIERS

Features

- ◆ Ideal for printed circuit board
- ◆ Reliable low cost construction utilizing molded plastic technique
- ◆ High temperature soldering guaranteed: 260°/10 seconds at 5 lbs., (2.3kg) tension
- ◆ Small size, simple installation
- ◆ High surge current capability
- ◆ Glass passivated chip junction
- ◆ Leads solderable per MIL-STD-202, Method 208

Mechanical Data

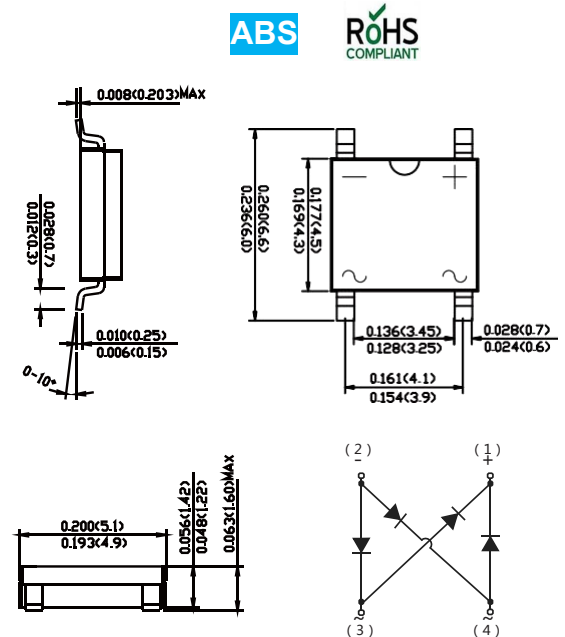
Case : JEDEC ABS Molded plastic body

Terminals : Solder plated, solderable per MIL-STD-750, Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any

Weight : 0.003 ounce, 0.098 grams



Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	RABS2	RABS4	RABS6	RABS8	RABS10	UNITS
Marking Code		RCD RABS2	RCD RABS4	RCD RABS6	RCD RABS8	RCD RABS10	
Maximum repetitive peak reverse voltage	V _{RRM}	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	140	280	420	560	700	V
Maximum DC blocking voltage	V _{DC}	200	400	600	800	1000	V
Maximum average forward rectified current On glass-epoxy P.C.B.(Note1) On aluminum substrate(Note2)	I _{F(AV)}	0.8 1.0					A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	30					A
Maximum instantaneous forward voltage drop per leg at 0.4A	V _F	1.3					V
Maximum DC reverse current T _A =25°C T _A at rated DC blocking voltage =100°C	I _R	5 500					uA uA
Typical thermal resistance(NOTE 3)	Rθ _{JL}	25					°C/W
	Rθ _{JA}	75					
Maximum reverse recovery time (NOTE 4)	trr	150		250	500		ns°
Operating temperature range	T _J	-55 to +150-					C°
storage temperature range	T _{STG}	55 to +150					C

NOTES:1.On glass epoxy P.C.B. mounted on 0.05x0.05"(1.3x1.3mm) pads.

2.On aluminum substrate P.C.B. with an area of 0.8"x0.8"(20x20mm) mounted on 0.05X0.05"(1.3X1.3mm) solder pad.

3.Thermal resistance from junction to ambient and junction to lead mounted on P.C.B. with 0.2X0.2"(5X5mm) copper pads.

4.Reverse recovery condition $I_F=0.5A$, $I_R=1.0A$, $t_{rr}=0.25A$.

FIG.1 FORWARD DERATING CURVE

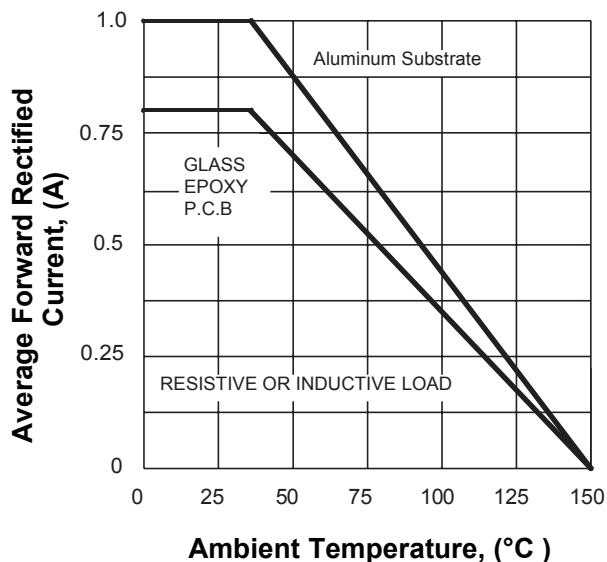


FIG.2 PEAK FORWARD SURGE CURRENT

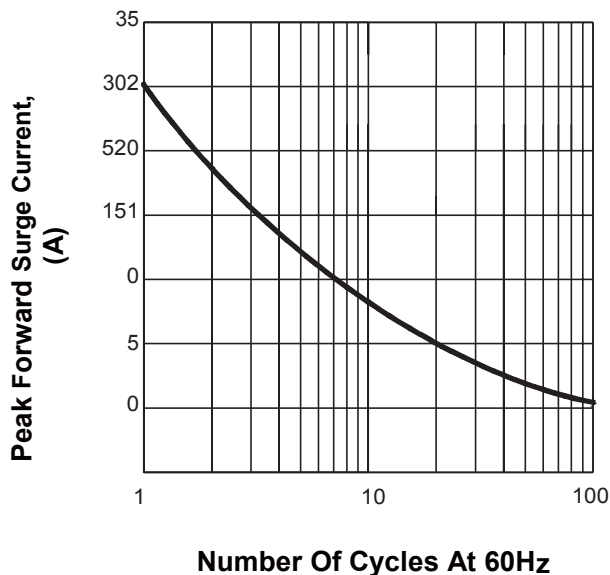


FIG.3 TYPICAL FORWARD CHARACTERISTICS

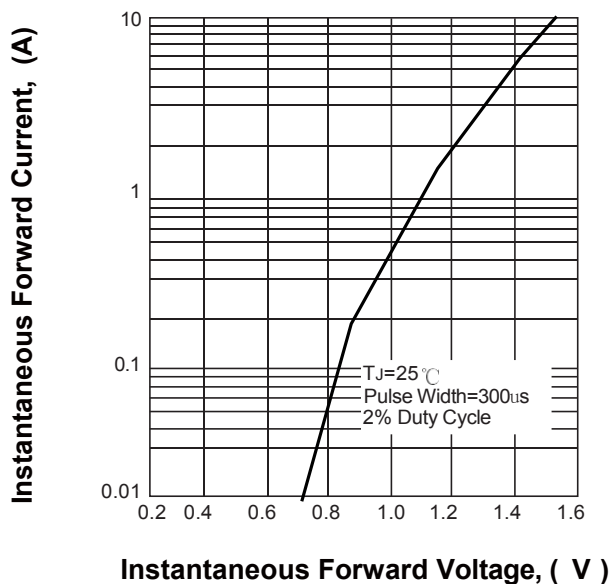
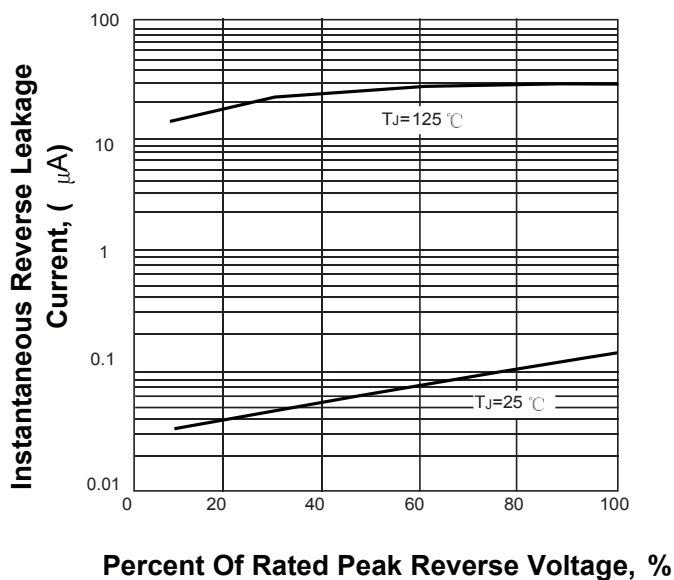
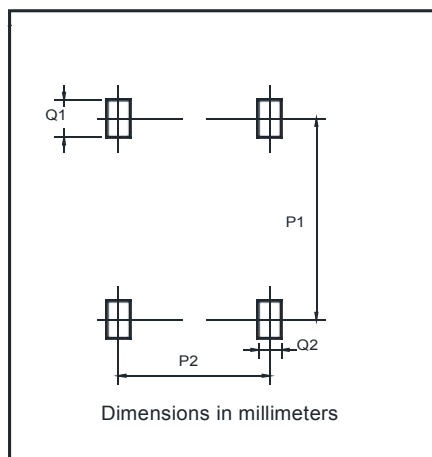


FIG.4 TYPICAL REVERSE CHARACTERISTICS



The curve above is for reference only.



Dim	Min
P1	5.72
P2	4.00
Q1	1.00
Q2	0.90